

PRODUCT INFORMATION LETTER

PIL MMS-MIC/13/8156 Dated 16 Oct 2013

STM32F2xx EMI characteristics update

Sales Type/product family label	STM32F2xx products			
Type of change	Product electrical spec. change			
Reason for change	datasheets correction			
Description	EMI characteristic table in STM32F2xx datasheets will be updated in order to be in line with the real silicon performance.			
Forecasted date of implementation	09-Nov-2013			
Forecasted date of samples for customer	09-Oct-2013			
Forecasted date for STMicroelectronics change Qualification Plan results availability	09-Oct-2013			
Involved ST facilities	NA			

DOCUMENT APPROVAL

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PRODUCT INFORMATION LETTER

STM32F2xx EMI characteristics update

MMS - Microcontrollers Division (MCD)

Dear Customer,

In order to provide a better service to our customers and to improve our STM32F2xx products datasheets, ST MCD division is informing you about an update of EMI characteristics, detailed on datasheets.

What is the change?

EMI characteristic table in STM32F2xx datasheets will be updated as following in order to be in line with the real silicon performance:

Symbol	Parameter	Conditions	Monitored frequency band	Current Datasheet values Max Vs [f _{HSE} /f _{CPU}] 8/120MHz	New Datasheet values Max Vs [f _{HSE} /f _{CPU}] 25/120MHz	Unit
S _{EMI} Peal		VDD = 3.3 V, TA = 25 °C, LQFP176 package, conforming to SAE J1752/3 EEMBC, code running with ART enabled, peripheral clock disabled	0.1 to 30MHz	21		
			30 to 130MHz	28		dBuV
			130MHz to 1GHz	31	25	
			SAE EMI Level	4	4	-
	Peak level	VDD = 3.3 V, TA = 25 °C, LQFP176 package, conforming to SAE J1752/3 EEMBC, code running with ART enabled, PLL spread spectrum enabled, peripheral clock disabled	0.1 to 30MHz	21	28	dBuV
			30 to 130MHz	15	26	
			130MHz to 1GHz	14	22	
			SAE EMI Level	3.5	4	-

Why?

Due to typographic errors, current STM32F2xx products datasheets contain

wrong values that do not reflect the real silicon image. Datasheets are revised

to be aligned with actual silicon performance.

When?

The new datasheets will be implemented on week 45 2013.

How will the change be qualified?

This change is already qualified using the standard STMicroelectronics

Corporate Procedures for Quality and Reliability.

What is the impact of the change?

- Form: no change

- Fit: no change

- Function: no change

How can the change be seen?

STM32F2xx new datasheets versions will implement this change:

STM32F20x datasheet revision will be changed from rev10 to rev11,

- STM32F21x datasheet revision will be changed from rev8 to rev 9.

We remain available for any complementary information you may need

concerning this change.

With our sincere regards.

Michel Buffa

Microcontroller Division General Manager

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